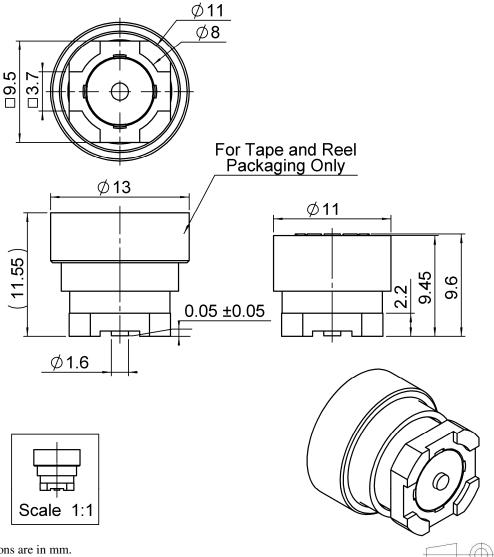
## STRAIGHT MALE RECEPTACLE FOR SMT **SNAP TYPE - REEL PACKAGE**

R328.424.002

Series: BMR-SPRING



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATING (μm)
BODY CENTER CONTACT OUTER CONTACT	BRASS BRASS	NPGR; BBR NPGR
INSULATOR GASKET	PEEK	
OTHERS PARTS	BERYLLIUM COPPER, PTFE	BBR
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#### **PACKAGING**

Standard	Unit	Other	
250	'W' option	Contact us	

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

Impedance  $50 \Omega$ 

Frequency 0-8 GHz

VSWR 1.2\* + 0.0000 x F(GHz) Maxi Insertion loss 0.1\*\*  $\sqrt{F(GHz)}$  dB Maxi RF leakage - ( TBT - F(GHz)) dB Maxi

Voltage rating 500 Veff Maxi Dielectric withstanding voltage Insulation resistance 5000 M $\Omega$  mini

#### **ENVIRONMENTAL**

Operating temperature -40/+120 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

#### OTHER CHARACTERISTICS

Assembly instruction NA

Others:

\*up to 3GHz, 0-6GHz:1.25Max,0-8GHz:1.35
\*Measured by one bullet+two connectors
\*,\*\*Coaxial Transmission Line Only

#### MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

18 N mini
18 N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight **5.0900** g

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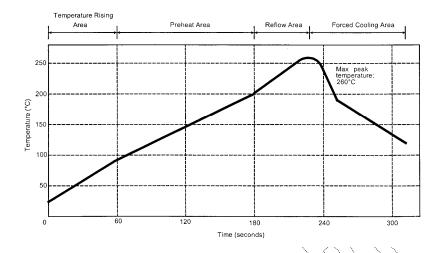
Series: BMR-SPRING

#### **SOLDER PROCEDURE**

- 1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component . Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .

Verification of solder joints and position of the component by visual inspection.

#### **TEMPERATURE PROFILE**



		•
Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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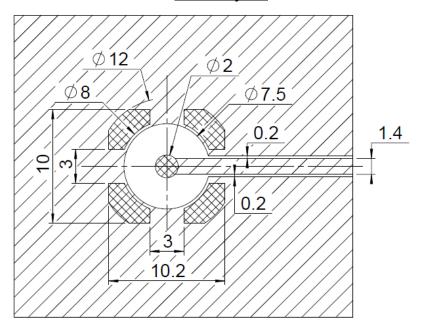
# STRAIGHT MALE RECEPTACLE FOR SMT

**SNAP TYPE - REEL PACKAGE** 

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#### **PCB** Layout

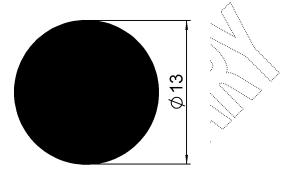


Land for solder paste

Pattern

COPLANAR LINE: Pattern and signal are on the same side. Thickness of PCB = 1.5 mm(double sides). The material of PCB is RO4350. The solder resist should be printed except for the land pattern on the PCB.

### **Shadow of receptacle for video camera**



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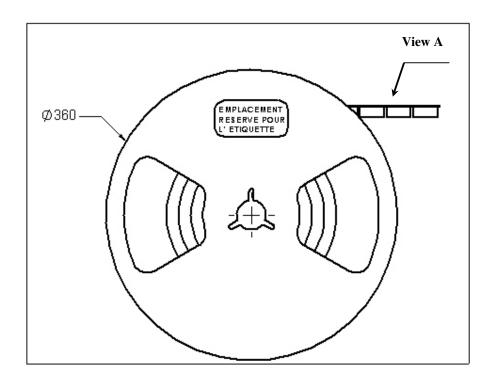


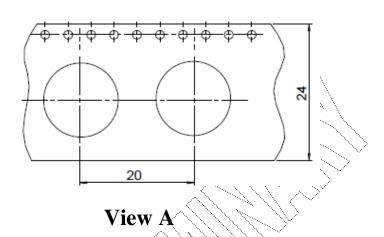
# STRAIGHT MALE RECEPTACLE FOR SMT SNAP TYPE - REEL PACKAGE

R328.424.002

Series: BMR-SPRING

#### **PACKAGE**





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